

**In the Specification:**

Please amend the title of the application as follows:

~~METHOD AND APPARATUS FOR FORMING A PLANARIZING PADS FOR~~  
PLANARIZATION OF MICROELECTRONIC SUBSTRATES

Please add a new section directly before "Technical Field" as follows:

**CROSS-REFERENCE TO RELATED APPLICATIONS**

This application is a divisional application of U.S. Patent Application No. 09/649,429, entitled "METHOD FOR FORMING A PLANARIZING PAD FOR PLANARIZATION OF MICROELECTRONIC SUBSTRATES," filed August 28, 2000, now U.S. Patent No. \_\_\_\_\_, issued \_\_\_\_\_; and is related to U.S. Patent Application No. \_\_\_\_\_ [Attorney Docket No. 108298404US2], entitled "APPARATUSES FOR FORMING A PLANARIZING PAD FOR PLANARIZATION OF MICROELECTRONIC SUBSTRATES," filed February 5, 2004, which is a divisional application of U.S. Patent Application No. 09/649,429, both of which are herein incorporated by reference in their entireties.